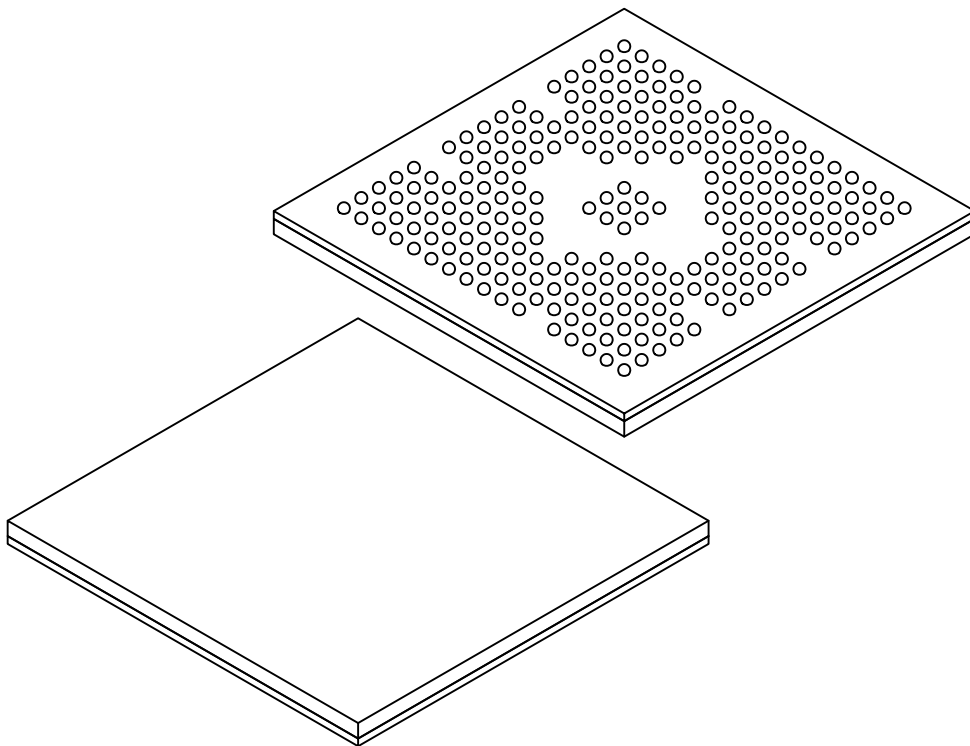


243-Ball Thin Fine-Pitch Ball Grid Array (4TB) - 16x16x1.23 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		243		
Pitch	e		0.80 BSC		
Overall Height	A		–	–	1.23
Ball Height	A1		–	0.21	0.312
Mold Thickness	M		0.51	0.56	0.61
Overall Length	D		16.00 BSC		
Ball Array Length	D2		12.80 BSC		
Overall Width	E		16.00 BSC		
Ball Array Width	E2		12.80 BSC		
Ball Diameter	b		0.35	0.40	0.45

Notes:

1. Terminal A1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.